

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	353	257/E23.051.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:35
L2	14	257/E23.001.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:36
L3	1219	257/E23.101.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:36
L4	682	257/E23.102.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:36
L5	171	257/E23.11.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:36
L6	296	257/E23.111.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:36
L7	178	257/E23.113.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:36
L8	1638	1 2 4 5 6 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:59

## EAST Search History

L9	1167	3 not 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:59
S1	1252	257/712.ccls.	USPAT	OR	OFF	2006/01/08 15:12
S2	2574	257/712.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 15:12
S3	1300	257/713.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 15:12
S4	1109	257/717.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 15:12
S5	4379	S2 S3 S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:00
S6	20	US-6506681-\$.DID. OR US-5250843-\$.DID. OR US-6558978-\$.DID. OR US-6437990-\$.DID. OR US-6168970-\$.DID. OR US-4975659-\$.DID. OR US-4498530-\$.DID. OR US-5623394-\$.DID. OR US-5757620-\$.DID. OR US-5587882-\$.DID.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 15:14
S7	1	("20030082847").PN.	US-PGPUB; USPAT	OR	OFF	2006/01/08 15:14
S8	1	("20030015788").PN.	US-PGPUB; USPAT	OR	OFF	2006/01/08 15:15
S9	1	("20030127715").PN.	US-PGPUB; USPAT	OR	OFF	2006/01/08 15:15
S10	1	("20030197252").PN.	US-PGPUB; USPAT	OR	OFF	2006/01/08 15:15

## EAST Search History

S11	24	S6 S7 S8 S9 S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 15:15
S12	574	S5 and carrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 15:25
S13	139	S5 and (carrier SAME (ceramic or organic))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 15:57
S14	435	S12 not S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 16:11
S15	596	S12 S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 16:11
S16	3804	S5 not S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/08 17:13
S17	1845	S5 not S15	USPAT	OR	OFF	2006/01/08 16:12
S18	1959	S16 not S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 08:21
S19	1068	(semiconductor or ic or chip or die or (integrated adj circuit)) and ((heat adj sink) or ((heat or thermal) adj dissipator) or ((heat or thermal) adj spreader)) and ((thermal adj adhesive) or ((thermal or heat or thermally) near3 paste))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 08:26

## EAST Search History

S20	2995	(semiconductor or ic or chip or die or (integrated adj circuit)) and ((heat adj sink) or ((heat or thermal) adj dissipator) or ((heat or thermal) adj spreader)) and (((thermal adj adhesive) or ((thermal or heat or thermally) near3 (resin or paste))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/05 17:53
S21	2574	257/712.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:06
S22	1300	257/713.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 08:26
S23	1109	257/717.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 08:26
S24	4379	S21 S22 S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 08:26
S25	2648	S20 not S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 08:50
S26	1229	S20 not S24	USPAT	OR	OFF	2006/01/09 08:27
S27	1419	S25 not S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 08:50

## EAST Search History

S28	1569	(semiconductor or ic or chip or die or (integrated adj circuit)) and ((heat or thermal) near3 (radiating or radiator or radiate)) and ((thermal adj adhesive) or ((thermal or heat or thermally) near3 (resin or paste)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:04
S29	1022	S28 not S20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 09:30
S30	968	S29 not S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 09:30
S31	283	(heat adj sink) and ((heat adj spreader) with (diamond or si or sic or mo or ceramic))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:06
S32	13	S31 and (((thermal adj adhesive) or ((thermal or heat or thermally) near3 (resin or paste))) with ((ag near3 epoxy) or thermoplastic or polymer or solder))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:26
S33	1	("5094769").PN.	USPAT	OR	OFF	2006/01/09 11:29
S34	1	("5167851").PN.	USPAT	OR	OFF	2006/01/09 11:29
S35	1	("5098609").PN.	USPAT	OR	OFF	2006/01/09 11:29
S36	109	(semiconductor or ic or chip or die or (integrated adj circuit)) and ((heat adj sink) or ((heat or thermal) adj dissipator) or ((heat or thermal) adj spreader)) and (carrier with (ceramic and organic))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 12:05
S37	3671	(semiconductor or ic or chip or die or (integrated adj circuit)) and ((heat adj sink) or ((heat or thermal) adj dissipator) or ((heat or thermal) adj spreader)) and ((thermal adj adhesive) or ((thermal or heat or thermally) near3 (resin or paste)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/05 17:42

## EAST Search History

S38	296	S37 and @pd>"20060108"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/05 17:43
S39	23073	(semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) same ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:23
S40	3877	"257"/\$6.ccls. and (semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) same ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 15:08
S41	3291	"257"/\$6.ccls. and (semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) with ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/05 17:59
S42	2237	"257"/\$6.ccls. and (semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) with ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 15:08
S43	2141	"257"/\$6.ccls. and (semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) with ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB)	USPAT	OR	ON	2006/07/05 17:59

## EAST Search History

S44	331	"257"/\$6.ccls. and (semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) same ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB) and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/05 18:03
S45	3546	S40 not S44	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/05 18:04
S46	2289	S40 not S44	USPAT	OR	ON	2006/07/05 18:04
S47	3014	S41 not S44	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/05 19:47
S48	1947	S41 not S44	USPAT	OR	ON	2006/07/05 18:04
S49	3291	"257"/\$6.ccls. and (semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) with ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/05 19:47
S50	331	"257"/\$6.ccls. and (semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) same ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB) and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 14:57
S51	1067	S49 not S50	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/05 19:48

## EAST Search History

S52	38	(power adj density) with (heat\$3) with lower with higher	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 14:55
S53	3	((power adj density) with (heat\$3) with lower with higher) and @pd>"20060705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 14:56
S55	11	("257"/\$6.ccls. and (semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) same ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB) and (heat adj sink))and @pd>"20060705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 14:58
S56	2713	257/712.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:00
S57	1396	257/713.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:00
S58	1155	257/717.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:00
S59	4581	S56 S57 S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:00



## EAST Search History

S60	202	S59 and @pd>"20060109"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:00
S61	199	((semiconductor or ic or chip or die or (integrated adj circuit)) and ((heat or thermal) near3 (radiating or radiator or radiate)) and ((thermal adj adhesive) or ((thermal or heat or thermally) near3 (resin or paste)))) and @pd>"20060109"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:05
S62	186	S61 not S60	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/26 15:05
S63	61	((heat adj sink) and ((heat adj spreader) with (diamond or si or sic or mo or ceramic))) and @pd>"20060109"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 15:07
S64	145	("257"/\$6.ccls. and (semiconductor or ic or chip or die or (integrated adj circuit)) and (((low or small or smaller or less or decreased) near3 density) same ((high or large or larger or greater or great or more or bigger or increased) near3 density)) and (carrier or wafer or board or PCB)) and @pd>"20060705"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/26 16:35